To power the technologies of the future, the world’s most creative companies require solutions to meet demanding design requirements. Cadence is a pivotal leader in electronic design, building upon three decades of computational software expertise to deliver software, hardware, and IP that our customers use to turn design concepts into reality for the most dynamic market applications including consumer, hyperscale computing, 5G communications, automotive, mobile, aerospace, industrial, and healthcare. We create computational software for Intelligent System Design™.

**Electronic Design**

Cadence offers the broadest, most integrated end-to-end design solutions to help today’s electronic designers do their best work creating tomorrow’s products, for:

- Silicon design creation, simulation, implementation, and signoff of analog and digital circuits; off-the-shelf design IP; and IC packaging, including machine learning-enhanced EDA tools and machine learning-enabled EDA flows.
- System design of advanced packaging, safe and secure embedded software, and PCBs; analysis of electromagnetic and electrothermal effects of semiconductors, packages, boards, and systems; and co-optimization with semiconductor devices.
- Intelligence IP for design of inference processing in edge devices.

**Corporate Facts**

<table>
<thead>
<tr>
<th>Founded</th>
<th>1988</th>
</tr>
</thead>
<tbody>
<tr>
<td>Corporate Headquarters</td>
<td>2655 Seely Ave. San Jose, CA 95134 USA</td>
</tr>
<tr>
<td>Nasdaq Symbol</td>
<td>CDNS</td>
</tr>
<tr>
<td>Primary Business</td>
<td>Computational software for electronic design and system analysis</td>
</tr>
</tbody>
</table>
Product Offering

Analog and Digital IC Design

As a leader in custom, analog, RF, and mixed-signal design enablement, we provide a complete solution starting with tools and methodologies that enable fast and accurate entry of design concepts all the way through verifying the designs before they are produced in silicon. By selectively automating aspects of custom IC design, we allow engineers to focus on precision-crafting their designs and the effects on circuit performance.

For designing the digital parts of chips, over the past few years we have introduced entirely new, next-generation tools that improve productivity and speed the design process. This comprehensive tool family speeds the full design cycle from front-end design all the way to final silicon signoff convergence.

The Cadence® IP portfolio includes pre-designed and configurable blocks that can be integrated quickly into chip designs, freeing the design team from re-designing these elements. This portfolio includes Tensilica® DSPs for AI, vision, audio, IoT, and baseband applications; Denali® memory and storage IP; and controllers for the latest standard interfaces including PCI Express® (PCIe®), USB, and Ethernet.

System Verification

The Cadence Verification Suite supports the company’s Intelligent System Design strategy, which enables system and semiconductor companies to create complete, differentiated end products more efficiently. The Verification Suite is comprised of best-in-class core engines, verification fabric technologies, and solutions that increase design quality and throughput, fulfilling verification requirements for a wide variety of applications and vertical segments. This unique mixture of software-based solutions with hardware accelerators delivers the shortest turnaround time and predictable quality. Our technology offers the only proven path for system-level power and signal integrity. We also offer Verification IP (VIP) to verify interface and memory standards.

IC Packaging Design

The complexity and performance requirements of today’s semiconductor packages continue to increase while design resources remain static for most organizations—placing a premium on efficiency and productivity. Our IC packaging and cross-domain co-design automation provide efficient solutions in system-level co-design and advanced mixed-signal packaging, delivering the automation and accuracy to expedite the design process.

PCB Design

We offer leading PCB layout and routing technologies used by a wide range of designers, from casual hobby designers to companies developing extremely demanding innovative new products. Our PCB design solutions enable shorter, more predictable design cycles with greater integration of component design and system-level simulation for a constraint-driven flow for right-first-time design. The right system design software and the right system simulation and analysis software can make it easy to ensure design connectivity and eliminate unnecessary system re-spins to correct connectivity mismatches in your multi-board PCB system designs.

CFD Analysis

Cadence now offers computational fluid dynamics (CFD) tools that involve two computationally heavy steps, meshing and solving. Meshing divides both solid surfaces and fluid volumes into small pieces onto which physics can be solved. Solving applies fundamental fluid dynamics equations to the mesh in order to capture the macro effects of the fluid on the system. Predicting real-world product performance during the design process is paramount for selecting the optimal design of complex systems.

A Great Place to Work

Cadence is committed to being a socially responsible company by building the innovative technologies that transform lives around the world. We pride ourselves on our “One Cadence—One Team” company culture that drives market- and industry-leading innovation and business success. Cadence is recognized as a Great Place to Work around the world, including as one of Fortune Magazine’s “100 Best Companies to Work For” over the last seven years. We have also earned global recognitions for our efforts around our environmental, social, and governance strategies.
Revenue

FY 12-20 Revenue

Executive Management

Lip-Bu Tan
Chief Executive Officer

Anirudh Devgan, PhD
President

Tom Beckley
Senior Vice President and General Manager, Custom IC & PCB Group

Paul Cunningham, PhD
Senior Vice President and General Manager, System & Verification Group

Alinka Flaminia
Senior Vice President, and Chief Legal Officer

Tina Jones
Senior Vice President, Global Human Resources

Nimish Modi
Senior Vice President, Marketing & Business Development

Chin-Chi Teng, PhD
Senior Vice President and General Manager, Digital & Signoff Group

John Wall
Senior Vice President and Chief Financial Officer

Neil Zaman
Senior Vice President, Worldwide Field Operations

For More Information

Investor Relations: +1.408.944.7100
Media Relations: +1.408.914.6884

Revenue

$2.68B

2012: 1.3
2013: 1.5
2014: 1.6
2015: 1.7
2016: 1.8
2017: 1.9
2018: 2.1
2019: 2.3
2020: 2.68